Material Declaration Datasheet
Restriction on Hazardous Substances (RoHS) Compliance

Manufacturer: Intel Corporation   Date: 21 September, 2011

Equipment type: CPU Board   Product: Lead-free Second Level Interconnect (SLI)

Product Codes: **DN2800MT**

RoHS Definitions:

Quantity limit of 0.1% by mass (1,000 ppm) for: Lead (Pb); Mercury; Hexavalent Chromium; Polybrominated Biphenyls (PBB); Polybrominated Diphenyl Ethers (PBDE). Quantity limit of 0.010% by mass (100 ppm) for Cadmium.

Intel understands RoHS compliance requires Lead and other materials banned in RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU, or (2) an approved or pending exemption applies. Note - RoHS implementation details are subject to change.

RoHS Declaration:

This product is RoHS directive compliant but does contain Lead, a RoHS restricted substance per the definitions above. This product uses the following applicable RoHS technology exemptions: 6c, **7a, 7c**

This product has been verified to be in conformance with EU directive 2002/95/EC as currently understood. To the best of our knowledge the information contained in this declaration is true and correct.

Level A Materials and Substances:

This product does contain materials listed in Annex A of the EIA/EICTA/JGPSSI Material Composition Declaration Guide above the threshold level of 1,000 ppm as listed below:

Lead/Lead Compounds.

Level B Materials and Substances:

This product does contain materials listed in Annex B of the EIA/EICTA/JGPSSI Material Composition Declaration Guide above the threshold level of 1,000 ppm as listed below: Arsenic/Arsenic Compounds,

Bismuth/Bismuth Compounds, Brominated Flame Retardants (other than PBBs or PBDEs).

COMMENTS

1. The data reported for Level A and B materials and substances are based on analytical testing of a representative sample product. Individual test results may vary due to differences in production and/or sensitivities of analytical testing methods. Data shown reflect analytical testing intended to validate Intel's RoHS compliance systems. Intel's certification of RoHS compliance at the homogenous material level is based on Supplier Declarations of Conformance.
2. This declaration is based on the product specified, with all product skus of this product eligible to be covered by this declaration.
3. Material concentration data in parts per million (ppm) is representative of all product skus within the product family.
4. Material mass can be estimated by multiplying concentration (in ppm) by product weight.
5. The remainder of this product consists of non-reportable metals (i.e., copper, iron, tin), epoxy resin and other non-metal materials.

关于符合中国《电子信息产品污染控制管理办法》的声明

Management Methods on Control of Pollution from
Electronic Information Products
(China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称 (Parts)	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
主板组件 Motherboard Assembly	×	○	○	○	○	○

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的限量要求以下。

○：Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.

×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准规定的限量要求。

×：Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.

对销售之日的所售产品,本表显示我公司供应链的电子信息产品可能包含这些物质。注意：在所售产品中可能会也可能不会含有所有所列的部件.

This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of sale of the enclosed product. Note that some of the component types listed above may or may not be a part of the enclosed product.

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